



**TARGET THICKNESS: 0.093"**  
**NUMBER OF LAYERS: 08**

# MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

<b>8 Layer StackUp (0.093") L08-093-2oz2oz</b>		<b>Thickness (inches)</b>
<b>Layer 1</b>	<b>2 oz foil plated to approximate* thickness 0.0038"</b>	0.0038
Prepreg	Bonding ply (1x1080, 2x2116) Average Dielectric Constant 4.5	0.0106
<b>Layer 2</b>	<b>2 oz foil thickness</b>	0.0028
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 3</b>	<b>2 oz foil thickness</b>	0.0028
Prepreg	Bonding ply (1x1080, 2x2116) Average Dielectric Constant 4.5	0.0106
<b>Layer 4</b>	<b>2 oz foil thickness</b>	0.0028
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 5</b>	<b>2 oz foil thickness</b>	0.0028
Prepreg	Bonding ply (1x1080, 2x2116) Average Dielectric Constant 4.5	0.0106
<b>Layer 6</b>	<b>2 oz foil thickness</b>	0.0028
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 7</b>	<b>2 oz foil thickness</b>	0.0028
Prepreg	Bonding ply (1x1080, 2x2116) Average Dielectric Constant 4.5	0.0106
<b>Layer 8</b>	<b>2 oz foil plated to approximate* thickness 0.0017"</b>	0.0038
*Thickness does not include soldermask or surface finish"		<b>0.0968</b>

**NOTES:**